

Cooling Failure Mitigation for an Electronics Enclosure

Abstract

A system for permitting orderly shutdown of electronic components. The system
5 includes an enclosure populated with one or more electronic components. A fan
positioned within the enclosure generates an airflow across the one or more electronic
components, the airflow being cooled by a heat exchanger. A phase change material is
positioned within the enclosure to absorb heat from the airflow in the event of a failure
associated with the heat exchanger.